

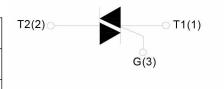
DESCRIPTION:

With high ability to withstand the shock loading of large current, **BTA26-TP** triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended focus on inductive load.



MAIN FEATURES

Symbol	Value	Unit
I _{T(RMS)}	25	Α
V _{DRM} /V _{RRM}	600/800/1200/1600	V



ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T _{stg}	-40-150	$^{\circ}$ C
Operating junction temperature range		Tj	-40-125	$^{\circ}$
Repetitive peak off	-state voltage (Tj=25℃)	VDRM	600/800/1200/1600	V
Repetitive peak rev	verse voltage (Tj=25℃)	V _{RRM}	600/800/1200/1600	V
RMS on-state current	TO-220A(Ins)/ TO-220F(Ins) (Tc=70°C) TO-220C/ TO-220B(Non-Ins) (Tc=85°C) TO-262 (Tc=50°C) TO-3P(Ins) (Tc=95°C)	I _{T(RMS)}	25	A
Non repetitive surge peak on-state current (full cycle, F=50Hz)		Ітѕм	250	Α
I ² t value for fusing (tp=10ms)		I ² t	340	A ² s

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Critical rate of rise of on-state current $(I_G = 2 \times I_{GT})$	dI/dt	50	A/µs
Peak gate current	Івм	4	Α
Average gate power dissipation	P _{G(AV)}	1	W
Peak gate power	P _{GM}	10	W

ELECTRICAL CHARACTERISTICS (T_j =25 $^{\circ}$ C unless otherwise specified)

V_{DRM} /V_{RRM}: 600/800V

Symbol	Test Condition	Quadrant		Value		Unit
				BW	CW	Oilit
Іст	V _D =12V R _L =33Ω	I - II -III	MAX	50	35	mA
V _{GT}	VD=12V RL=33()	I - II -III	MAX	1	.3	V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2		V
IL IG=1.2IGT	1 -4 01	I -III	MAX	80	70	mA
	IG = I.ZIGT	II	IVIAA	100	80	IIIA
lн	I _T =100mA		MAX	75	50	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	1000	500	V/µs

V_{DRM} /V_{RRM}: 1200/1600V

Symbol	Test Condition Quadran	Quadrant		Value		Unit
		Quadrant		BW	CW	Offic
Іст	V _D =12V R _L =33Ω	I - II -III	MAX	50	35	mA
V _{GT}	VD - 12V KL-3312	I - II -III	MAX	1	.5	V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2		V
I.	I _G =1.2I _{GT}	I -III	MAX	90	70	m A
l L		II	IVIAA	100	80	mA
lн	I _T =100mA		MAX	80	60	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	1500	1000	V/µs



V_{DRM} /V_{RRM}: 600/800V

Symbol	Test Condition Quadrant	Quadrant		Value		Unit
		Quadrant		В	С	Unit
1	V _D =12V R _L =33Ω	I - II -III	MAY	50	25	A
I _{GT}		IV	MAX	70	50	mA
V _{GT}		ALL	MAX	1	.3	V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	ALL	MIN	0.2		V
1.	I _G =1.2I _{GT}	I -III-IV	MAX	80	70	m 1
l IL		II	IVIAA	100	90	mA
lн	I _T =100mA		MAX	75	60	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	500	200	V/µs

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V _{TM}	I _{TM} =35A tp=380µs	T _j =25℃	1.5	V
I _{DRM}		T _j =25℃	5	μΑ
I _{RRM}	V _D =V _{DRM} V _R =V _{RRM}	T _j =125℃	3	mA

THERMAL RESISTANCES

Symbol	Parame	Value	Unit	
R _{th(j-c)}		TO-220A(Ins)	1.5	
	junction to case(AC)	TO-220C/ TO-220B(Non-Ins)	1.1	
		TO-220F(Ins)	1.7	_°℃/ W _
		TO-262	2.1	
		TO-3P(Ins)	0.67	



FIG.1: Maximum power dissipation versus RMS on-state current

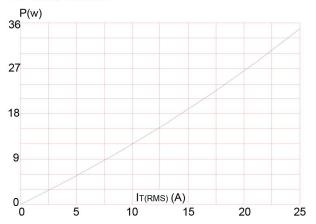


FIG.3: Surge peak on-state current versus number of cycles

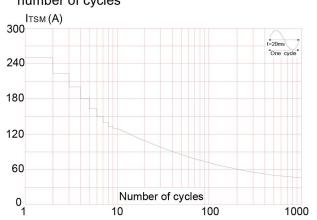


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of l²t (dl/dt < 50A/μs)

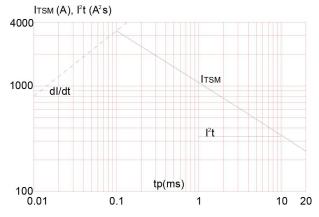


FIG.2: RMS on-state current versus case temperature

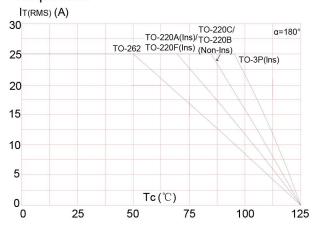


FIG.4: On-state characteristics (maximum values)

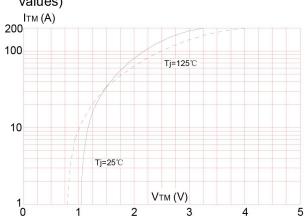


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

